

Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifiers

eSMP® Series



Top view

Bottom view

SMF (DO-219AB)

Cathode  Anode

LINKS TO ADDITIONAL RESOURCES



3D Models

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	3.0 A
V_{RRM}	120 V
I_{FSM}	60 A
V_F at $I_F = 3$ A ($T_A = 125$ °C)	0.64 V
T_J max.	175 °C
Package	SMF (DO-219AB)
Circuit configuration	Single

FEATURES

- Trench MOS Schottky technology
- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified available
 - Automotive ordering code: base P/NHM3
- Compatible to SOD-123W package case outline
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT
HALOGEN
FREE

TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

MECHANICAL DATA

Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: color band denotes the cathode end

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	V3FM12	UNIT
Device marking code		3MS	
Maximum repetitive peak reverse voltage	V_{RRM}	120	V
Maximum average forward rectified current (fig.1)	$I_{F(AV)}^{(1)}$	2.5	A
	$I_{F(AV)}^{(2)}$	3.0	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	60	A
Operating junction temperature range	$T_J^{(3)}$	-40 to +175	°C
Storage temperature range	T_{STG}	-55 to +175	

Notes

(1) Free air, mounted on FR4 PCB, 2 oz. standard footprint

(2) Mounted on FR4 PCB, 2 oz. 10 mm x 10 mm copper pad area

(3) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$

**ELECTRICAL CHARACTERISTICS** ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 1.5 A	T _A = 25 °C	V _F ⁽¹⁾	0.65	-	V
	I _F = 3.0 A			0.84	0.94	
	I _F = 1.5 A	T _A = 125 °C		0.55	-	
	I _F = 3.0 A			0.64	0.72	
Reverse current	V _R = 90 V	T _A = 25 °C	I _R ⁽²⁾	0.7	-	μA
		T _A = 125 °C		550	-	
	V _R = 120 V	T _A = 25 °C		-	100	
		T _A = 125 °C		950	3000	
Typical junction capacitance	4.0 V, 1 MHz		C _J	220	-	pF

Notes(1) Pulse test: 300 μs pulse width, 1 % duty cycle(2) Pulse test: Pulse width $\leq 5\text{ ms}$ **THERMAL CHARACTERISTICS** ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	V3FM12	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	125	$^{\circ}\text{C/W}$
	$R_{\theta JM}^{(3)}$	22	

Notes(1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$ (2) Device mounted on FR4 PCB, 2 oz. standard footprint, thermal resistance $R_{\theta JA}$ – junction-to-ambient(3) Device mounted on 10 mm x 10 mm pad size area footprint; thermal resistance $R_{\theta JM}$ – junction-to-mount**ORDERING INFORMATION** (Example)

PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V3FM12-M3/H	0.015	H	3000	7" diameter plastic tape and reel
V3FM12-M3/I	0.015	I	10 000	13" diameter plastic tape and reel
V3FM12HM3/H ⁽¹⁾	0.015	H	3000	7" diameter plastic tape and reel
V3FM12HM3/I ⁽¹⁾	0.015	I	10 000	13" diameter plastic tape and reel

Note

(1) AEC-Q101 qualified

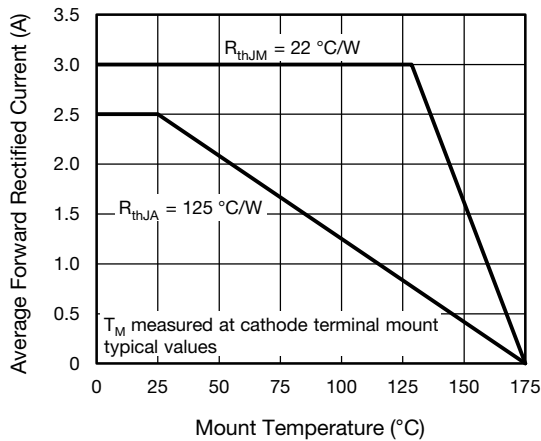
RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

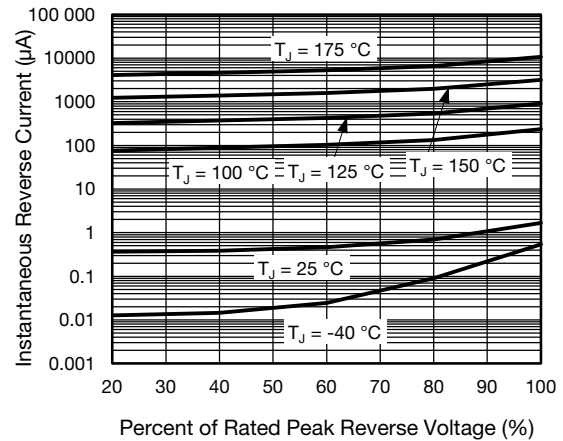


Fig. 4 - Typical Reverse Leakage Characteristics

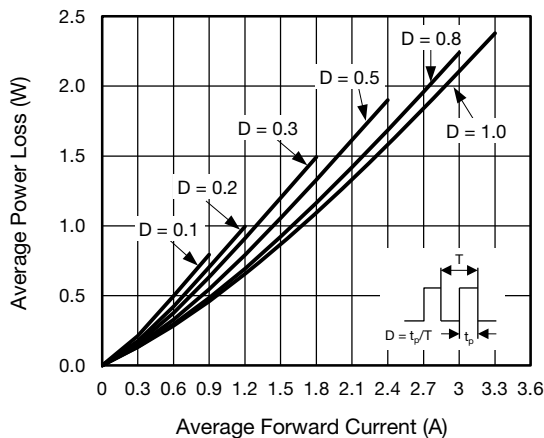


Fig. 2 - Average Power Loss Characteristics

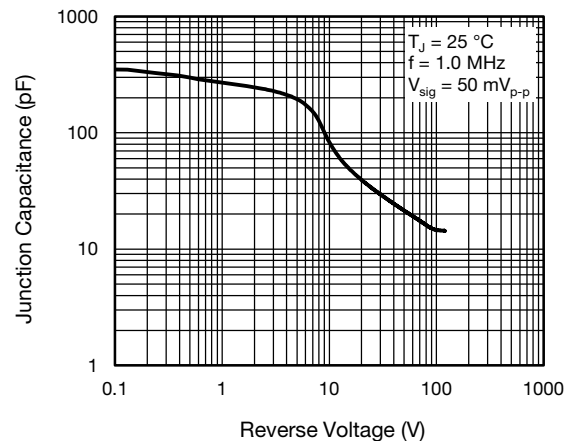


Fig. 5 - Typical Junction Capacitance

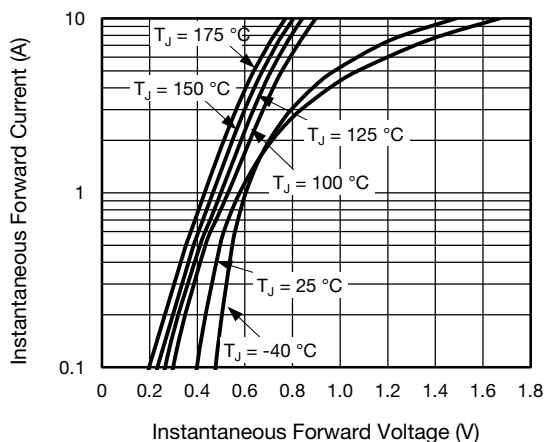


Fig. 3 - Typical Instantaneous Forward Characteristics

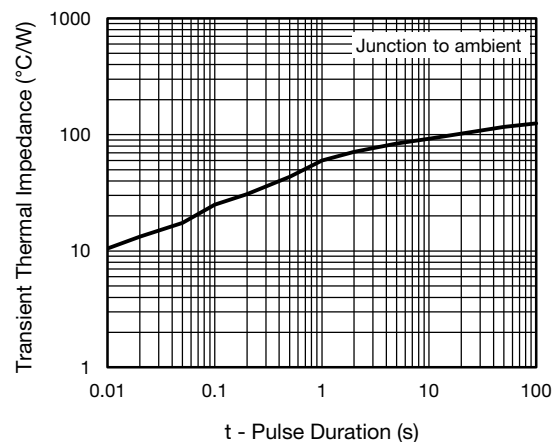
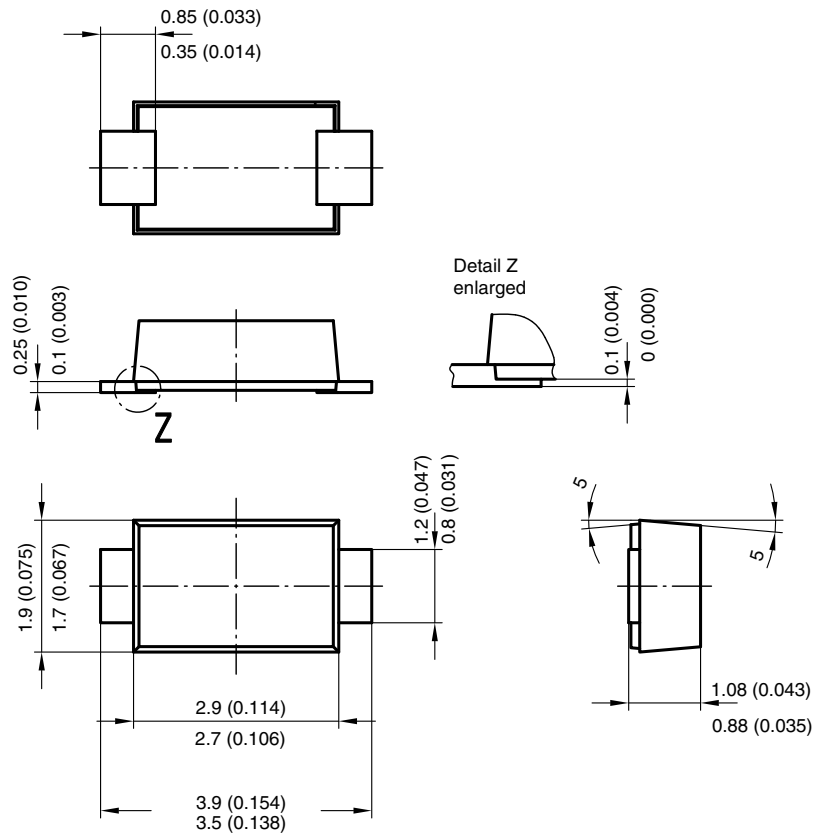
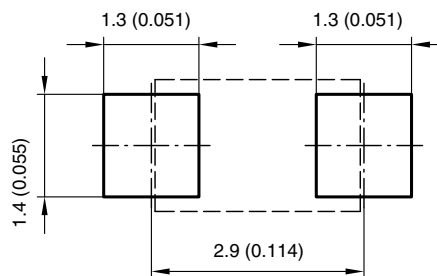


Fig. 6 - Typical Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS in millimeters (inches)


Foot print recommendation:



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17247



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